

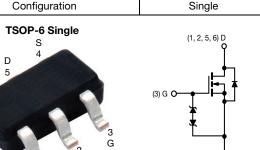


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Vishay Siliconix

Automotive N-Channel 40 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY			
V _{DS} (V)	40		
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.032		
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.042		
I _D (A)	8		
Configuration	Single		



FEATURES

- TrenchFET® power MOSFET
- Typical ESD protection 800 V
- AEC-Q101 qualifiedd
- 100 % Rg and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>





Marking Code: 8M

ORDERING INFORMATION			
Package	TSOP-6		
Lead (Pb)-free and Halogen-free	SQ3418AEEV-T1-GE3		

N-Channel MOSFET

ABSOLUTE MAXIMUM RATING	S ($T_C = 25 ^{\circ}C$, unles	s otherwise noted	l)	
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V_{DS}	40	V
Gate-Source Voltage		V _{GS}	± 20	V
Continuous Drain Current	T _C = 25 °C ^a		8	
	T _C = 125 °C		5	
Continuous Source Current (Diode Conduction)		I _S	6	Α
Pulsed Drain Current ^b		I _{DM}	32	
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	5	
Single Pulse Avalanche Energy	L = U.T IIII	E _{AS}	1.2	mJ
Maximum Power Dissipation ^b	T _C = 25 °C	В	5	W
	T _C = 125 °C	P_{D}	1.6	
Operating Junction and Storage Temperature	re Range	T _J , T _{sta}	-55 to +175	°C

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient PC	CB Mount c	R _{thJA}	110	°C/W	
Junction-to-Foot (Drain)		R_{thJF}	30		

Notes

- a. Package limited.
- b. Pulse test; pulse width $\leq 300 \,\mu\text{s}$, duty cycle $\leq 2 \,\%$.
- c. When mounted on 1" square PCB (Fr-4 material).
- d. Parametric verification ongoing.



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PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT	
Static	,	1		<u> </u>	<u> </u>	<u> </u>		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0$, $I_D = 250 \mu A$		40	-	-	.,	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$		2.0	2.5	V	
Gate-Source Leakage	I _{GSS}	V _{DS} =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$		-	± 500	nA	
		V _{DS} =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 1	mA	
Zero Gate Voltage Drain Current		$V_{GS} = 0 V$	V _{DS} = 40 V	-	-	1		
	I _{DSS}	V _{GS} = 0 V	V _{DS} = 40 V, T _J = 125 °C	-	-	50	μΑ	
		V _{GS} = 0 V	V _{DS} = 40 V, T _J = 175 °C	-	-	150		
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 \text{ V}$	10	-	-	Α	
Drain-Source On-State Resistance a		V _{GS} = 10 V	I _D = 5 A	-	0.026	0.032	Ω	
	В	V _{GS} = 10 V	I _D = 5 A, T _J = 125 °C	-	-	0.050		
Drain-Source On-State Resistance *	R _{DS(on)}	V _{GS} = 10 V	I _D = 5 A, T _J = 175 °C	-	-	0.061		
		V _{GS} = 4.5 V	I _D = 4 A	-	0.032	0.042		
Forward Transconductance b	9fs	V _{DS} = 15 V, I _D = 4 A		-	13	-	S	
Dynamic ^b								
Input Capacitance	C _{iss}			-	528	-	pF	
Output Capacitance	Coss	$V_{GS} = 0 V$	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	-	112	-		
Reverse Transfer Capacitance	C _{rss}			-	76	-		
Total Gate Charge c	Qg			-	3.5	-		
Gate-Source Charge ^c	Q_{gs}	$V_{GS} = 4.5 \text{ V}$	$V_{DS} = 20 \text{ V}, I_D = 4 \text{ A}$	-	1.3	-	nC	
Gate-Drain Charge ^c	Q_{gd}			-	1.2	-		
Gate Resistance	R_g	f = 1 MHz		-	2.3	-	Ω	
Turn-On Delay Time ^c	t _{d(on)}			-	8	-		
Rise Time ^c	t _r	$V_{DD} = 20 \text{ V, } R_L = 4 \Omega$ $I_D \cong 5 \text{ A, } V_{GEN} = 10 \text{ V, } R_g = 1 \Omega$		-	8	-	ns	
Turn-Off Delay Time ^c	t _{d(off)}			-	15	-		
Fall Time ^c	t _f			-	7	-		
Source-Drain Diode Ratings and Chara	acteristics $T_C = 2$	25 °C b						
Pulsed Current ^a	I _{SM}			-	-	32	Α	
Forward Voltage	V _{SD}	I _F = 3 A, V _{GS} = 0		-	0.8	1.2	V	

Notes

- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?62975.

单击下面可查看定价,库存,交付和生命周期等信息

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